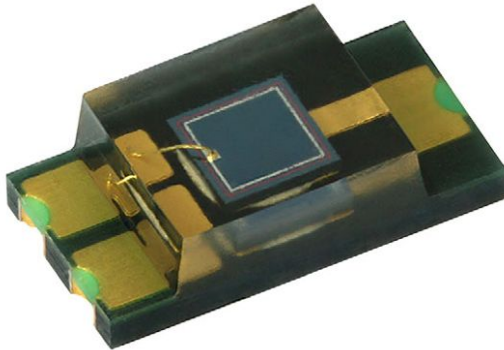


Silicon PIN Photodiode



FEATURES

- Package type: surface-mount
- Package form: 1206
- Dimensions (L x W x H in mm): 4 x 2 x 1.05
- Radiant sensitive area (in mm²): 0.85
- High photo sensitivity
- High sensitivity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 60^\circ$
- Floor life: 72 h, MSL 4, according to J-STD-020
- Lead (Pb)-free reflow soldering
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- High speed photo detector

DESCRIPTION

VEMD6010X01 is a high speed and high sensitive PIN photodiode. It is a small surface mount device (SMD) including the chip with a 0.85 mm² sensitive area detecting visible and near infrared radiation.

PRODUCT SUMMARY

COMPONENT	I_{ra} (μA)	φ (°)	$\lambda_{0.1}$ (nm)
VEMD6010X01	9.5	± 60	430 to 1100

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VEMD6010X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	1206

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	32	V
Power dissipation	$T_{amb} \leq 25^\circ\text{C}$	P_V	215	mW
Junction temperature		T_j	110	°C
Ambient temperature range		T_{amb}	-40 to +110	°C
Storage temperature range		T_{stg}	-40 to +110	°C
Soldering temperature	According to reflow solder profile Fig. 8	T_{sd}	260	°C
Thermal resistance junction to ambient	According to J-STD-051	R_{thJA}	270	K/W

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F	-	1	-	V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	32	-	-	V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}	-	1	3	nA
Diode capacitance	V _R = 0 V, f = 1 MHz, E = 0	C _D	-	12	-	pF
	V _R = 5 V, f = 1 MHz, E = 0	C _D	-	3.6	-	pF
Open circuit voltage	E _e = 1 mW/cm ² , λ = 950 nm	V _o	-	356	-	mV
Temperature coefficient of V _o	E _e = 1 mW/cm ² , λ = 950 nm	TK _{V_o}	-	-3.1	-	mV/K
Short circuit current	E _e = 1 mW/cm ² , λ = 950 nm	I _k	-	9	-	μA
Temperature coefficient of I _k	E _e = 1 mW/cm ² , λ = 950 nm	TK _{I_k}	-	0.1	-	%/K
Reverse light current	E _e = 1 mW/cm ² , λ = 950 nm, V _R = 5 V	I _{ra}	6.7	9.5	12.4	μA
Angle of half sensitivity		φ	-	± 60	-	°
Wavelength of peak sensitivity		λ _p	-	900	-	nm
Range of spectral bandwidth		λ _{0.1}	-	430 to 1100	-	nm
Rise time	V _R = 10 V, R _L = 1 kΩ, λ = 820 nm	t _r	-	100	-	ns
Fall time	V _R = 10 V, R _L = 1 kΩ, λ = 820 nm	t _f	-	100	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

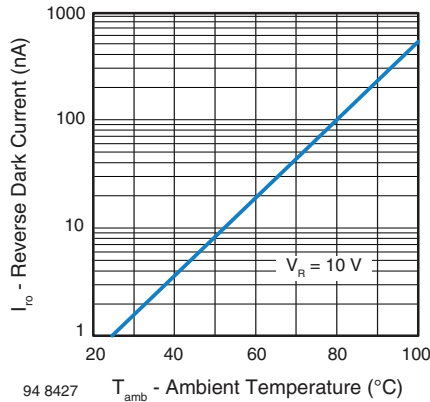


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

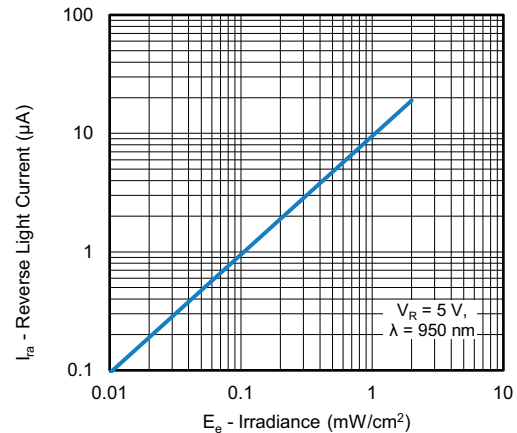


Fig. 3 - Reverse Light Current vs. Irradiance

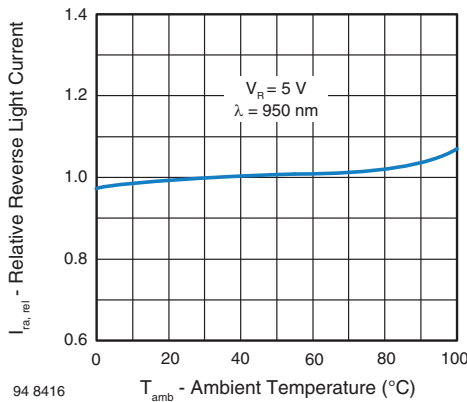


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

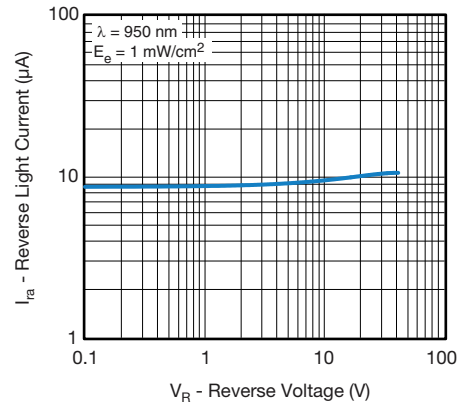


Fig. 4 - Reverse Light Current vs. Reverse Voltage

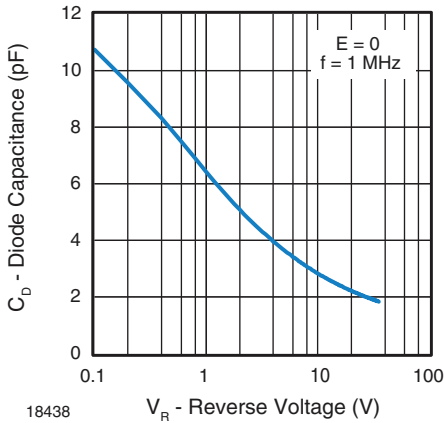


Fig. 5 - Diode Capacitance vs. Reverse Voltage

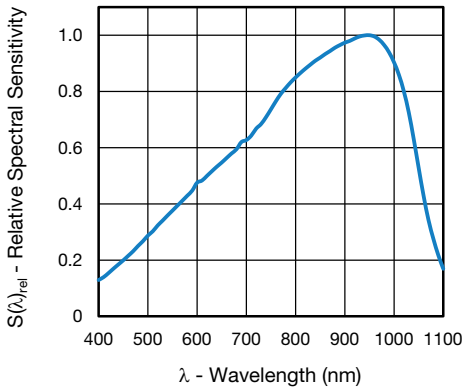
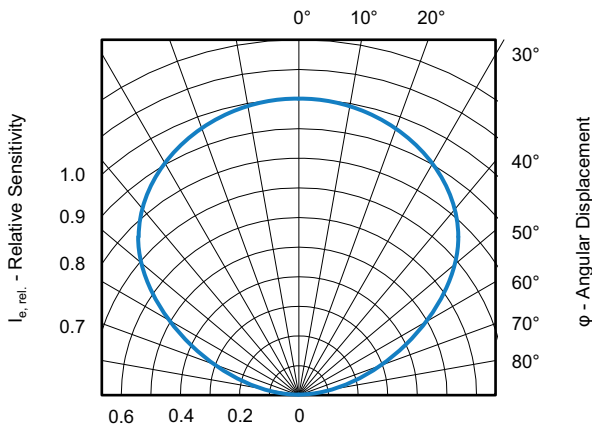


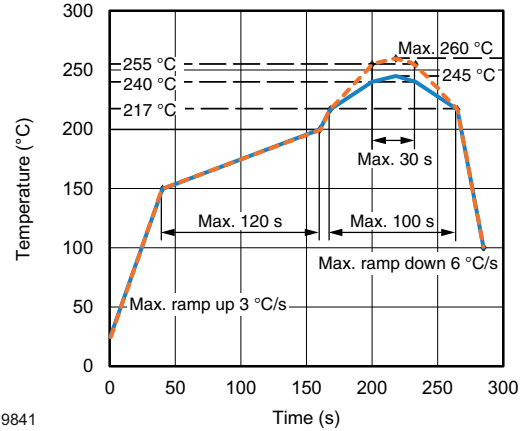
Fig. 6 - Relative Spectral Sensitivity vs. Wavelength



94 8013

Fig. 7 - Relative Sensitivity vs. Angular Displacement

REFLOW SOLDER PROFILE



19841

Fig. 8 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 72 h

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

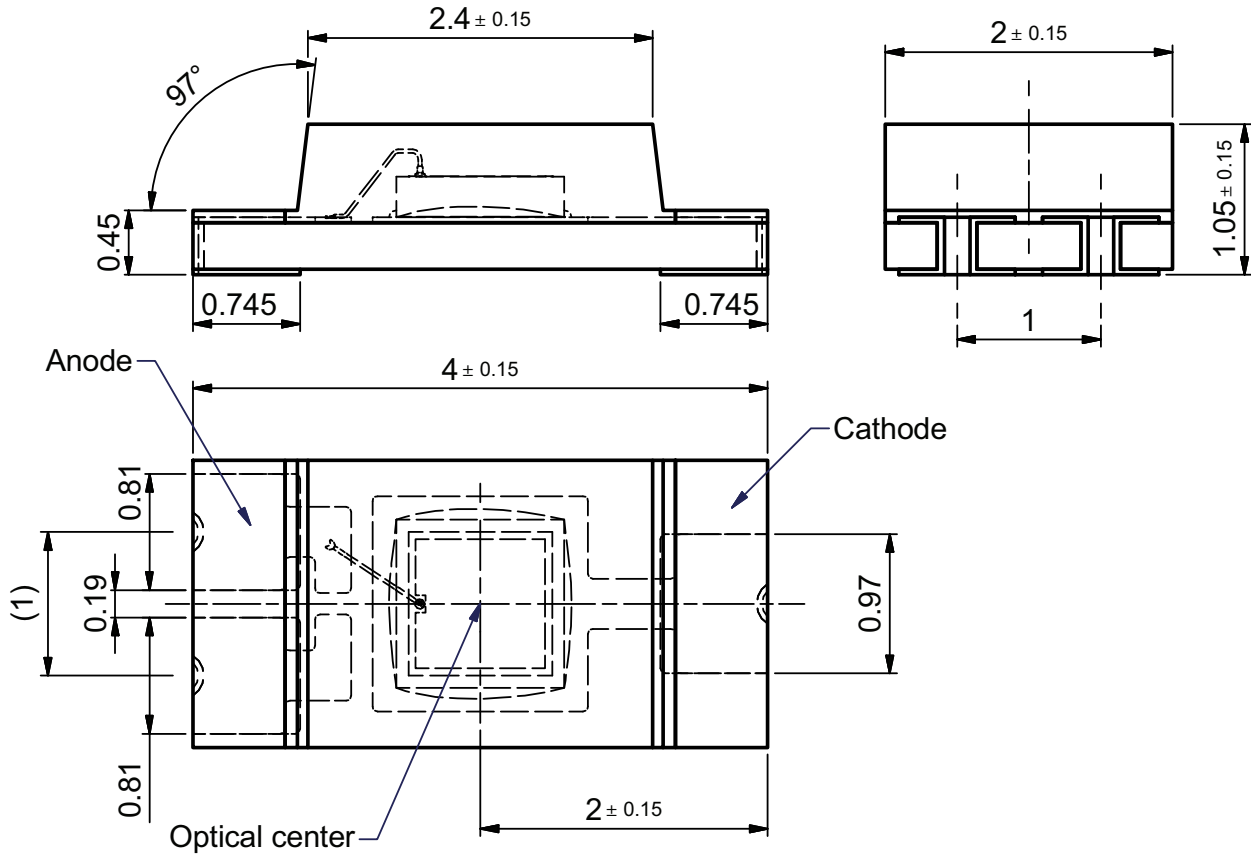
Moisture sensitivity level 4, acc. to J-STD-020.

DRYING

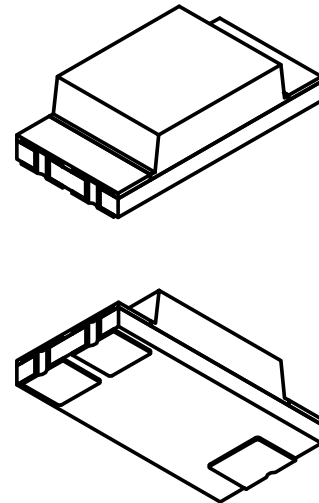
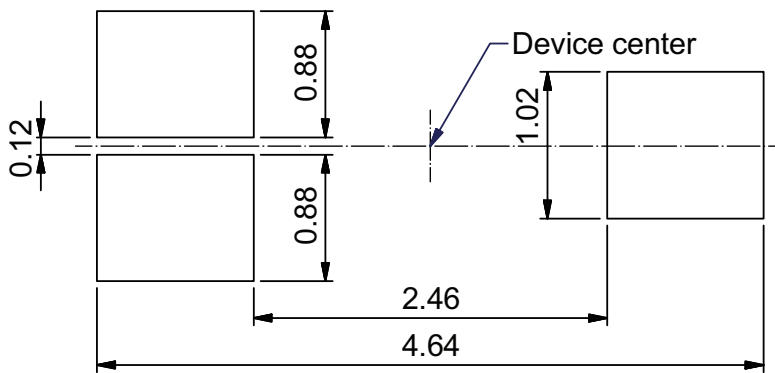
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), $RH < 5\%$.



PACKAGE DIMENSIONS in millimeters



Recommended solder pad footprint



Drawing-No. 6.541-5100.01-4
Preliminary issue 04.07.2013

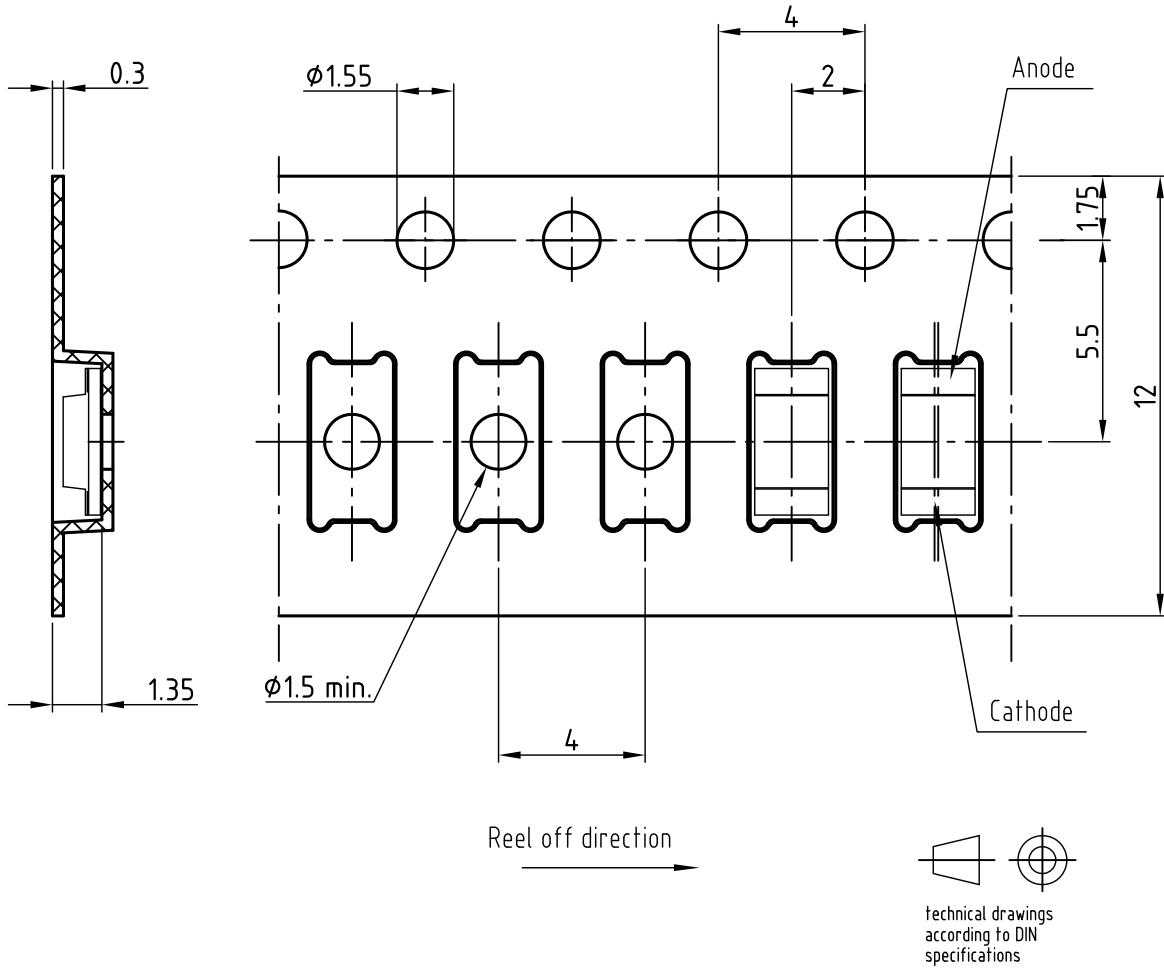


Technical drawings according to DIN specification.

Not indicated tolerances ± 0.1 mm



BLISTER TAPE DIMENSIONS in millimeters



Not indicated tolerances ±0.1

All dimensions in mm

Drawing refers to following Types: TEMD6010FX01

VEMD6x10X01

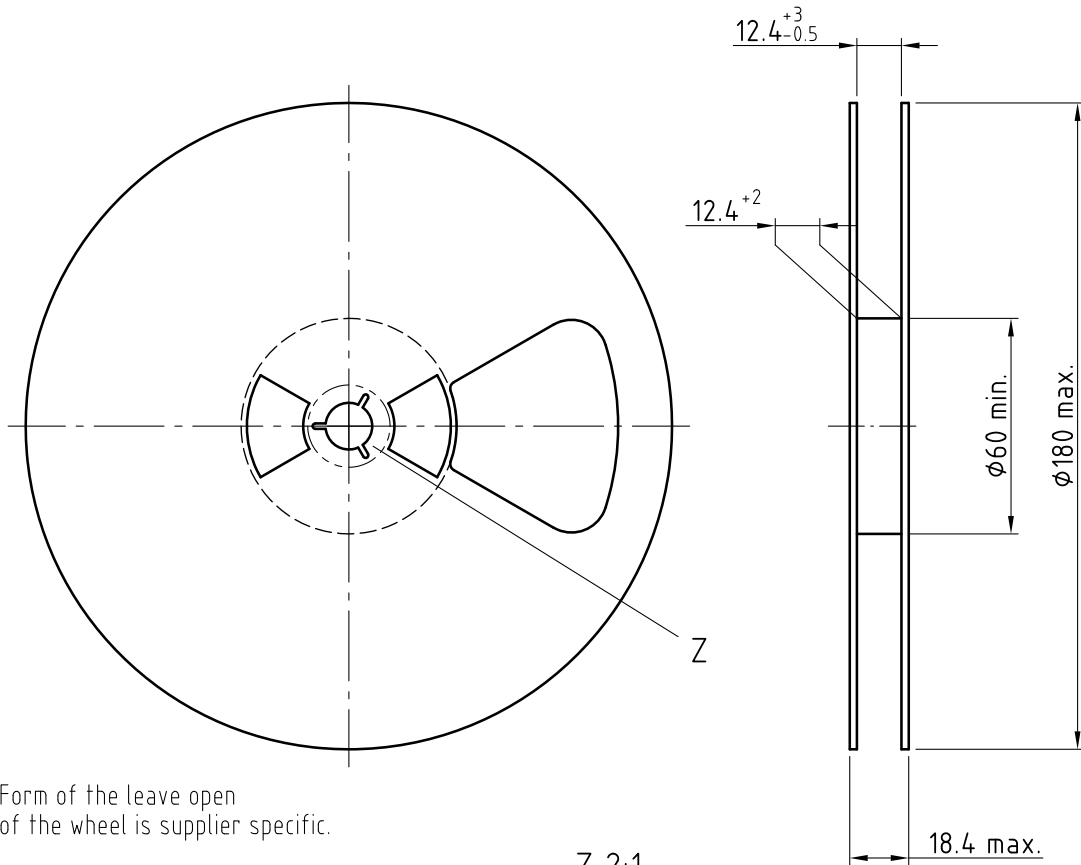
Drawing-No.: 9.700-5329.02-4

VEMD6x15X01

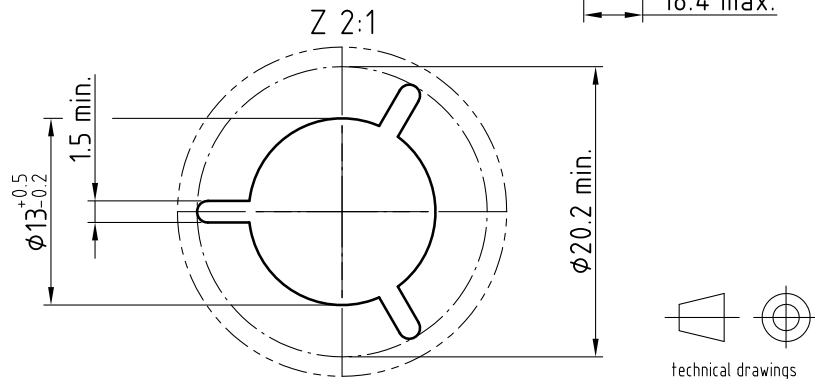
Prel Issue: 16.07.2013



REEL DIMENSIONS in millimeters



Form of the leave open of the wheel is supplier specific.



technical drawings according to DIN specifications

Drawing-No.: 9.800-5097.01-4

Issue: 1; 05.05.08

20874



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